

IN THE CLAIMS:

Please cancel claims 7-9 without prejudice to or disclaimer of the subject matter recited therein.

Please add new claims 16-18 as follows:

LISTING OF CURRENT CLAIMS

Claims 1-15. (Canceled)

16. (New) A flexible circuit tape comprising:

a plurality of tape type flexible printed circuits arranged in a plurality of separable rows, each tape type flexible printed circuit of the plurality of tape type flexible printed circuits having:

- 5 a) a flexible insulated layer having a thickness between 10 μ m and 75 μ m;
- b) a plurality of copper traces formed on the flexible insulated layer and having a thickness between 5 μ m and 40 μ m;
- c) a cover layer formed directly on a top of the flexible insulated layer and the plurality of copper traces and having a thickness between
- 10 10 μ m and 75 μ m, the cover layer having a plurality of hollow portions, connection terminals of each of the plurality of copper traces aligning with and being exposed through one of the plurality of hollow portions of the cover layer; and
- d) a plurality of sprocket holes located on each of two opposing sides
- 15 thereof,

wherein adjacent tape type flexible printed circuits of the plurality of tape type flexible printed circuits are separated by a plurality of parallel cutting lines, the plurality of parallel cutting lines are located between the plurality of sprocket holes of the adjacent tape type flexible printed circuits.

17. (New) The flexible circuit tape according to claim 16, wherein the cover layer is selected from a group of material consisting of polyimide, polyester, and photoimagible solder mask.

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18. (New) The flexible circuit tape according to claim 16, further comprising an electroplating layer located on of each of the connection terminals of each of the plurality of copper traces.